COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001
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ASSEMBLY VARIANT: 001

<table>
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<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP20978</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TID #: N/A</td>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 8/25/2017 11:52:02 PM</td>
<td>TEXAS INSTRUMENTS</td>
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